

SD100-11-31-221

5.1mm² Low Capacitance Silicon Photodiode

The SD100-11-31-221 is 2.54mm diameter active area silicon PIN photodiode, mounted in a hermetic 3-pin TO-5 metal where the anode and cathode are isolated from the package. The device is suitable for high speed and high sensitivity applications with the spectral range from 350 to 1100nm. It is ideal ideal for visible and near IR applications, including such AC applications as detection of pulsed LASER sources, LEDs, or chopped light.

Applications

Pulse Detectors
Optical Communications
Bar Code Readers
Optical Remote Control
Medical Equipment
High Speed Photometry

Features

Low Capacitance
Wide Dynamic Range
High Responsivity
5.1mm ² Active Area







Absolute Maximum Ratings

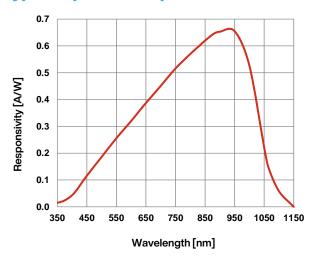
Parameter	Symbol	Min	Max	Unit			
Reverse Voltage	V _R	-	50	V			
Operating Temperature	T _{op}	-55	+150	°C			
Storage Temperature	T _{stg}	-40	+125	°C			
Package	TO-5						

Typical Electro-Optical Specifications at $T_A = 23 \text{ °C}$

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Active Area	-	A.A.	-	5.1	-	mm ²
Active Area Diameter	-	A.A. _ø	-	Ø2.54	-	mm
Spectral Range	Spot Scan	Δλ	350	-	1100	nm
Responsivity	λ =633nm, V _R =0V	R_{λ}	0.32	0.36	-	A/W
	λ =950nm, V _R =0V	R_{λ}	0.50	0.64	-	A/W
Capacitance	V _R =0V, F=1MHz	C」	-	15	-	pF
	V _R =50V, F=1MHz	C」	-	3	-	pF
Dark Current	V _R =50V	I _D	-	12	50	nA
Noise Equivalent Power	V _R =5V@ λ=950nm	NEP	-	1.3x10 ⁻¹³	-	W/√HZ
Rise Time*	λ =950nm, R _L =50 Ω , V _R =0V	t _R	-	9	-	μs
	λ =950nm, R _L =50 Ω , V _R =50V	t _R	-	13	-	nS

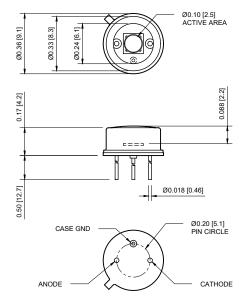
^{§*}Rise time of 10% to 90% is specified at 660nm wavelength light.

Typical Spectral Response



Mechanical Specifications

Units are in inches [mm]



PASSION FOR PHOTONICS DS SD100-11-31-221 Rev. A





General Care and Handling Instructions

Photodiodes:

Handling and Storage

- Handle Photodiodes gently to prevent damage.
- Avoid exposing Photodiodes to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

 Gently clean the glass (borosilicate or quartz window) using a 50/50 mixture of Methanol and isopropyl alcohol and a soft, optical-grade pad.

Special Considerations for Plastic or Epoxy Encapsulated Photodiodes

- Protect from intense light sources such as direct sunlight.
 Avoid exposure to harsh chemicals like THINNERS, ACETONE,
- and TRICHLOROETHYLENE.Cleaning with a 50/50 mixture of Methanol and isopropyl
- alcohol (IPA) is recommended. Cleaning in an ultrasonic bath is generally not recommended.

CdS Photocells:

Handling and Storage

- Handle CdS Photocells gently to prevent damage.
- Avoid exposing CdS Photocells to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

- Gently clean the glass or plastic covering using a 50/50
- mixture of Methanol and isopropyl alcohol and a soft, opticalgrade pad.

Special Considerations

 DO NOT use Vapor Phase Soldering or Reflow Soldering for CdS components.

Optocouplers and LEDs:

Handling and Storage

- Handle Optocouplers and LEDs gently to prevent damage.
 Avoid exposing the devices to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

 For plastic molded devices, cleaning with a 50/50 mixture of Methanol and isopropyl alcohol is recommended. Cleaning in an ultrasonic bath is generally not recommended.

Special Considerations

Avoid exposing plastic molded devices or epoxy glob top devices to harsh chemicals like THINNERS, ACETONE, and TRICHLOROETHYLENE.

Legal Disclaimer

Information in this data sheet is believed to be correct and reliable. However, no responsibility is assumed for possible inaccuracies or omission. Specifications are subject to change without notice.



Most of our standard catalog products are RoHS Compliant. Please contact us for details.

Electrostatic Discharge (ESD) Sensitivity:

All devices are considered ESD-sensitive. They are shipped in ESD protective packaging. When unpacking and using these products, anti-ESD precautions should be observed.

Lead Trimming and Bending:

Standard lead trimming after soldering is an acceptable practice; however, do not attempt to bend or modify the leads incorrectly, as it can damage the glass feed-through or the plastic encapsulant.

Soldering Instructions:

- Use a soldering iron with a tip temperature of 300°C max.
- Consult with your preferred solder manufacturer to determine a solder alloy and flux combination, as well as the reflow profile appropriate for your application.

General Precautions for all Devices

1. Moisture Prevention:

Ensure devices are stored in a dry environment to prevent moisture ingress, which can cause damage during soldering. Refer to J-STD-20 for guidance on proper baking procedures to prevent moisture related damage.

2. Lead Splaying:

If required, carefully splay the leads of the devices according to the specific application needs. Be cautious when splaying leads, as improper techniques may damage the device. Consult technical support or device datasheets for guidance on lead splaying.

3. Mechanical Stress:

Handle devices with care throughout the installation process to prevent damage.

4. Circuit Protection and Layout:

Optimize the circuit design and layout to ensure proper functioning and prevent damage to the devices. Include appropriate protection measures like ESD protection diodes, current-limiting resistors, and voltage regulation.

5. After-Sale Support:

For troubleshooting and device-specific inquiries, please consult with our technical support team. They can offer valuable guidance and suggestions on handling, operation, and application-related questions. To reach them, please contact the Advanced Photonix Applications group at Techsupport@advancedphotonix.com.

